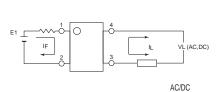
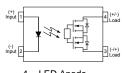
SUPSIC®

Parameter	Symbol	Rating	Units	
Load Voltage	VL	40	V	
Load Current	lL l	2.5	Α	
On-Resistance	Ron	0.055	Ω	
I/O Isolation Voltage	V/io	5000	Vrms	







- 2. LED Cathode
- 3.4. Drain(MOS FET)



DIP-4

SMD-4

SUPSiC PhotoRelays

- Long life (No limit on mechanical and electrical
- lifetime)Bounce-free switching
- · Higher speed and high frequency switching
- Higher sensitivity (less power consumption)
- Immunity to EMI or RFI

- No have voltaic arc, bounce, and noise More
- resistant to vibration and impact AC or DC load
- switching
- Small package size

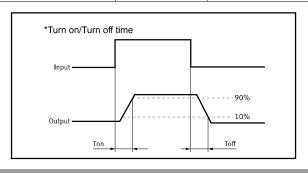
Applications

- Telecom/Datacom switching
- Multiplexers
- Meter reading systems
- Data acquisition
- Medical equipment
- Battery monitoring
- I/O Sub-Systems

- Robotics
- Aerospace
- Home/Safety security systems
- Process Control
- Energy Management
- Reed Relay EMR Replacement
- Programmable Controllers

TPYES

Category Output Rating Load Voltage Load Current		Doolsome	Part No.	Packing Quantity	
		Package	Fait No.		
AC/DC 40V	2.5A	DIP-4	GAQY211G3E	100pcs /tube	
	2.5A	SMD-4	GAQY211G3EH	2000pcs /reel	





Absolute Maximum Ratings (Ta = 25°C)

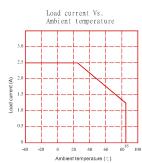
	Item	Symbol	Va l ue	Units	Note
	Continuous LED Current	I F	50	mA	
Input	Peak LED Current	I FP	1000	mA	f=100Hz, duty=1%
	LED Reverse Voltage	VR	5	V	
	Input Power Dissipation	Pın	75	mW	
Output	Load Voltage	V∟	40	V(AC peak or DC)	
	Load Current	l.	2.5	Α	
	Peak Load Current	Peak	5.0	Α	100ms(1 pulse)
	Output Power Dissipation	Pout	400	mW	
Total Power	Dissipation	P⊤	500	mW	
I/O Isolatio	n Voltage	V _{I/O}	5000	Vrms	RH=60%, 1min
Operating Te	emperature	Торг	-40 to 85	°C	
Storage Tem	perature	T _{stg}	-40 to 100	°C	
Pin Soldering	g Temperature	Tsol	260	℃	10 sec max.

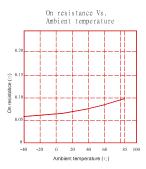
Electrical Characteristics (Ta = 25°C)

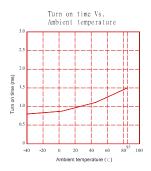
	Item	Symbol	MIN.	TYP.	MAX.	Units	Conditions
Input	LED Forward Voltage	VF		1.2	1.4	V	I⊧=10mA
	Operation LED Current	Fon		0.5	2.0	mA	
	Recovery LED Current	Foff		0.35	0.5	mA	
	Recovery LED Voltage	V _{Foff}	0.7			V	
							I⊧=5mA,I∟=100mA,
	On-Resistance	Ron		0.055	0.1	Ω	Time to flow is within 1 sec.
Output	Off-State Leakage Current	Leak			0.1	uA	V∟=Rating
	Output Capacitance	Cout		150		pF	V∟=0, f=1MHz
Transmis	Turn-On Time	Ton		0.8	1.5	ms	I⊧=5mA, I∟=100mA,
sion	Turn-Off Time	Toff		0.02	0.5	ms	
0	I/O Isolation Resistance	R _{I/O}	10 ¹⁰			Ω	DC500V
Coupled	I/O Capacitance	Ci/o		0.8	1.5	pF	f=1MHz

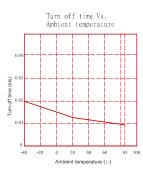
Please obey the following conditions to ensure proper device operation and resetting. Input LED current (Recommended value): IF \geq 5mA and \leq 30mA

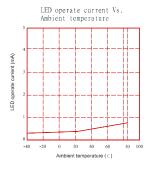
Engineering Data

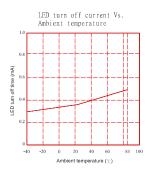


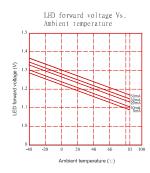


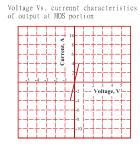


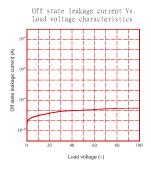


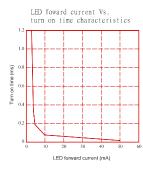


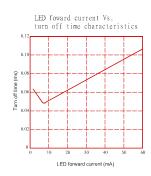


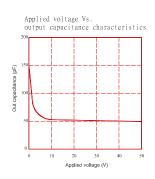












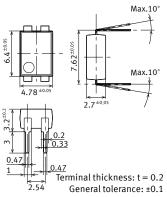


Dimensions and DIP-4 Package

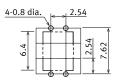
Unit: mm

Marking GAQY 211G3 YY=YEAR WW=WEEK

Surface mount terminal type



PC board pattern (BOTTOM VIEW)



Tolerance: ±0.1

DIP Tape dimensions

Unit: mm inch Tolerance: +0.2 +.007

Devices are packaged in a tube so that pin No. 1 is on the stopper B side. Observe correct orientation when mounting them on PC boards.

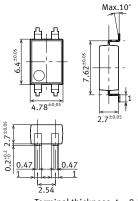




Dimensions and SMD-4 Package Unit: mm

Marking GAQY 211G3 YY=YEAR WW=WEEK

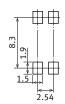
Surface mount terminal type



Terminal thickness: t = 0.2 General tolerance: ±0.1

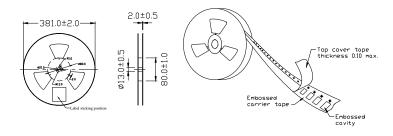
Recommended mounting pad

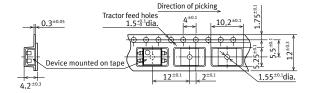
(TOP VIEW)



Tolerance: ±0.1

Tape dimensions (tape reel)

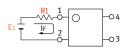


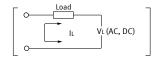




Using Methods

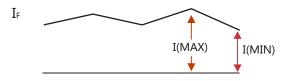
Examples of resistance value to control LED forward current (IF=5mA)





E1	R1 (Approx)
3.3V	300 Ω
5.0V	600 Ω
12V	1.9KΩ
24V	4.1K Ω

LED forward current must be more than 5mA, at I(MIN), and less than 30mA, at I(MAX).



Recommended Operating Conditions

Please obey the following conditions to ensure proper device operation and resetting. Input LED current (Recommended value):

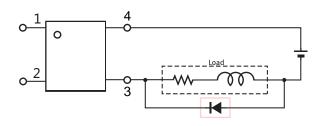
Characteristic	Symbol	Min	Тур.	Max	Unit
Forward current	lF	5.0	7.0	30	mA

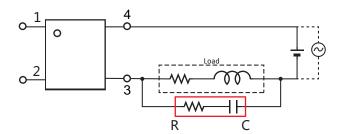
Protection Circuit

Output spike voltages:if an inductive load generates spike voltages which exceed heabsolute maximum rating, the spike voltage shall be limited.

Clamp diode is connected in parallel with the load. Absorb capacity with external diode.

CR Snubber is connected in parallel with the load. Absorb capacity with buffer capacity.





When adding diodes, buffer circuits (C-R), and other protections, they need to be installed near the MOS RELAY to be effective. Adding protection elements may result in a slow reset time, so adjust them according to the actual situation before use.

Note: When developing designs using this product, perform the expected performance of the equipment under the operating conditions recommended by the guidelines in this document. Continuous use under heavy loads (including, but not limited to, the application of high temperatures/current/voltage and significant changes in temperature, etc.) may result in deterioration of the reliability of this product.



Recommended Soldering Conditions

(a) Infrared reflow soldering:

■ Peak reflow soldering : 260°C or below (package surface temperature)

■ Time of peak reflow temperature : 10 sec
 ■ Time of temperature higher than 230°C : 30-60 sec
 ■ Time to preheat temperature from 180~190°C : 60-120 sec

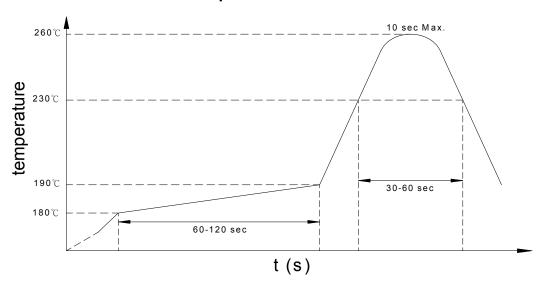
■ Time(s) of reflow: Two

■ Flux : Rosin flux containing small amount of chlorine (The

flux with a maximum chlorine content of 0.2 Wt% is

recommended.)

Recommended Temperature Profile of Infrared Reflow



(b) Wave soldering:

■ Temperature : 260°C or below (molten solder temperature)

■ Time : 10 seconds or less

■ Preheating conditions : 120°C or below (package surface temperature)

■ Time(s) of reflow : One

■ Flux: Rosin flux containing small amount of chlorine (The flux with a maximum

chlorine content of 0.2 Wt% is recommended.)

(c) Cautions:

■ Fluxes: Avoid removing the residual flux with freon-based and chlorine-based

cleaning solvent.

Avoid shorting between portion of frame and leads.